



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPG20N06S4L-26A	<b>Issued</b>	13. May 2021
<b>MA#</b>	MA002193004		
<b>Package</b>	PG-TDSON-8-10	<b>Weight*</b>	99.17 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.783	0.79	0.79	7899	7899
chip_2	inorganic material	silicon	7440-21-3	0.783	0.79	0.79	7899	7899
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		441	
	non noble metal	copper	7440-50-8	43.681	44.05	44.10	440451	441024
wire	non noble metal	aluminium	7429-90-5	0.802	0.81	0.81	8089	8089
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		927	
	plastics	epoxy resin	-	6.529	6.58		65833	
	inorganic material	silicondioxide	60676-86-0	39.357	39.69	46.36	396851	463611
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14080	14080
plating	inorganic material	phosphorus	7723-14-0	0.001			15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6081	6096
solder	non noble metal	tin	7440-31-5	0.048	0.05		481	
	noble metal	silver	7440-22-4	0.060	0.06		601	
	non noble metal	lead	7439-92-1	2.278	2.30	2.41	22972	24054
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.72	2.72	27213	27248
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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